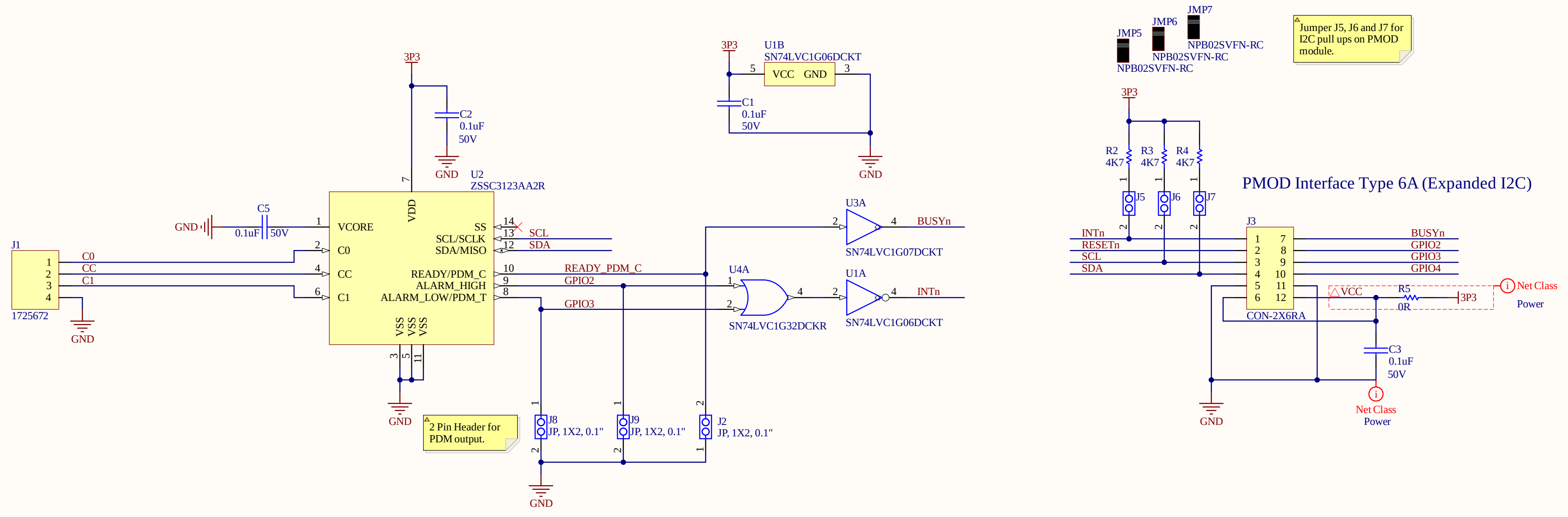
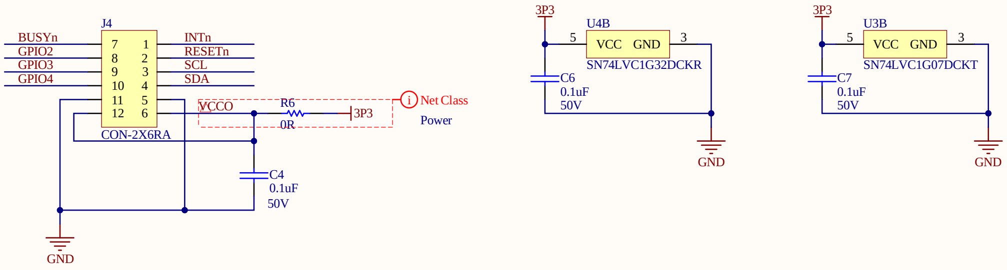


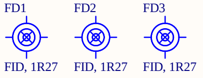


PMOD Interface Type 6A (expanded I2C)

Pin #	Signal	Direction (relative to host)	Alternate Signal	Direction (relative to host)
1	NC	In	INT	In
2	NC	Out	RESET	Out
3	SCL	In/Out	-	-
4	SDA	In/Out	-	-
5	GND	-	-	-
6	VCC	-	-	-
7	GPIO	In/Out	-	-
8	GPIO	In/Out	-	-
9	GPIO	In/Out	-	-
10	GPIO	In/Out	-	-
11	GND	-	-	-
12	VCC	-	-	-

CAP SENSOR

Rubber Foot, Black, 6.4mm dia, 2.1mm high
FOOT-000003-01



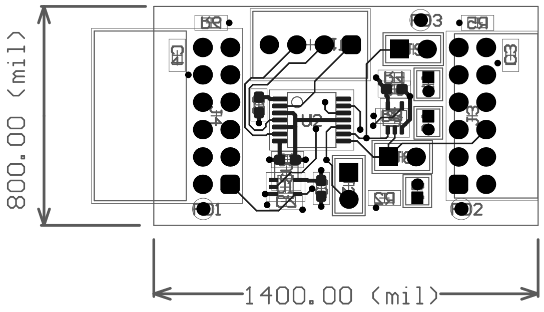
RENESAS

710 Slater Rd
Suite 200

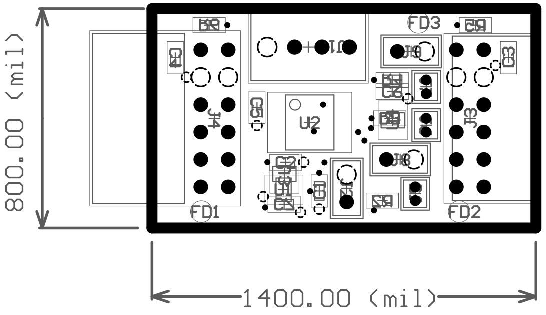
Morrisville
NC 27560

Title
US082-ZSSC3123EVZ Rev A.SchDoc

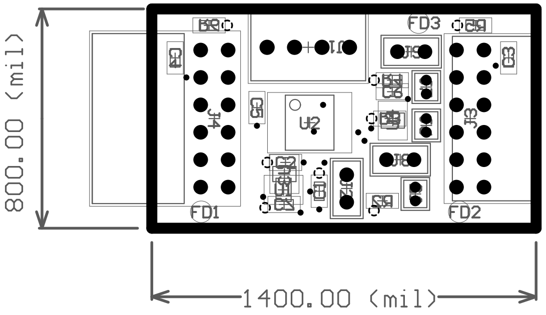
Size: B Number: Revision: A
Date: 11/6/2024 Sheet 1 of 1
File: US082-ZSSC3123EVZ Rev A.SchDoc



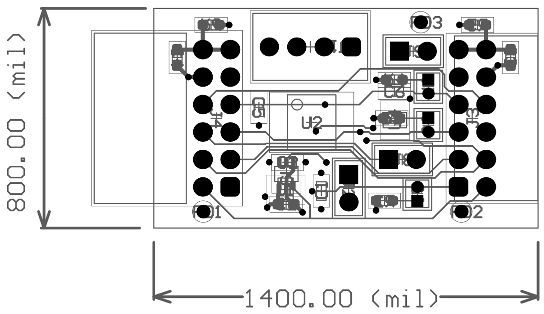
Filename: US082-ZSSC3123EVZ Rev A.PcbDoc
Date: 11/6/2024
Layer Name: Top Layer
Company: RENESAS



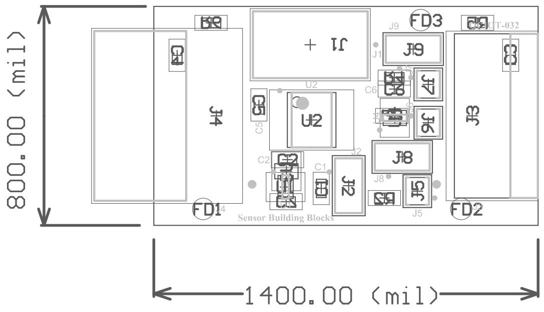
Filename:	US082-ZSSC3123EVZ Rev A.PcbDoc
Date:	11/6/2024
Layer Name:	Int1 (GND) (GND)
Company:	RENESAS



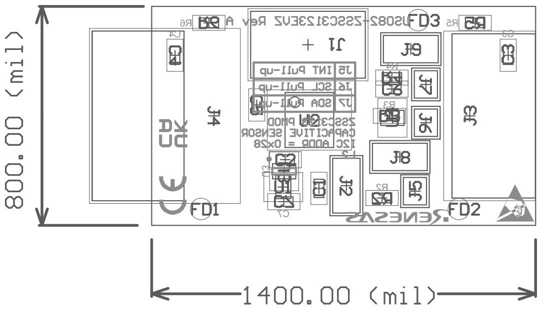
Filename: US082-ZSSC3123EVZ Rev A.PcbDoc
Date: 11/6/2024
Layer Name: Int2 (PWR) (3P3)
Company: RENESAS



Filename: US082-ZSSC3123EVZ Rev A.PcbDoc
Date: 11/6/2024
Layer Name: Bottom Layer
Company: RENESAS



Filename:	US082-ZSSC3123EVZ Rev A.PcbDoc
Date:	11/6/2024
Layer Name:	Top Silkscreen Overlay
Company:	RENESAS

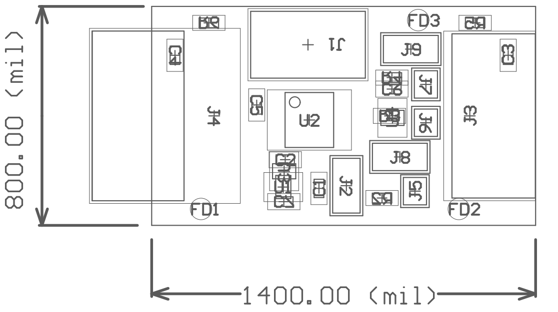


Filename: US082-ZSSC3123EVZ Rev A.PcbDoc

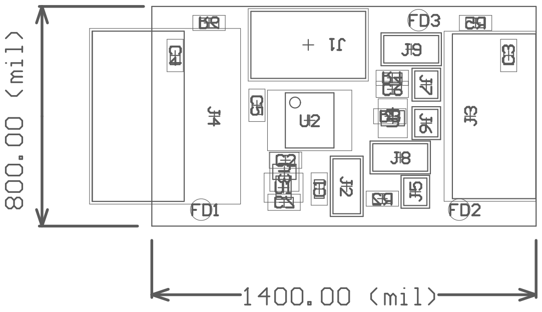
Date: 11/6/2024

Layer Name: Bottom Silkscreen Overlay

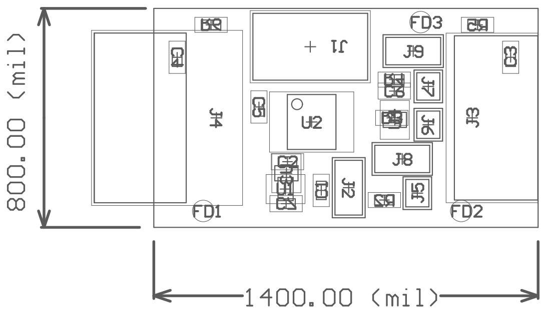
Company: RENESAS



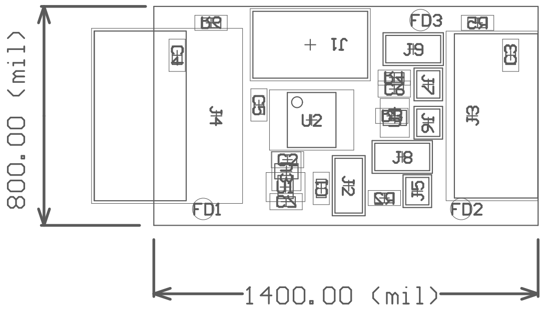
Filename:	US082-ZSSC3123EVZ Rev A.PcbDoc
Date:	11/6/2024
Layer Name:	Mechanical 1
Company:	RENESAS



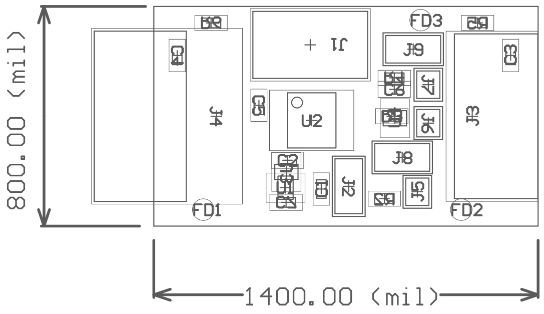
Filename: US082-ZSSC3123EVZ Rev A.PcbDoc
Date: 11/6/2024
Layer Name: Top Designator
Company: RENESAS



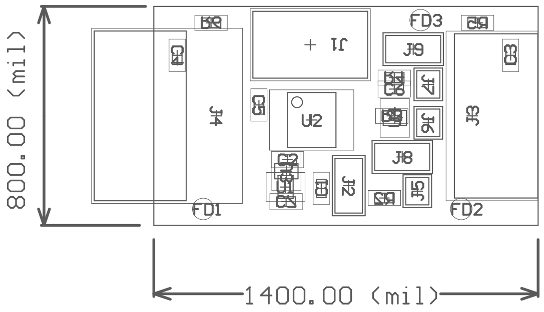
Filename: US082-ZSSC3123EVZ Rev A.PcbDoc
Date: 11/6/2024
Layer Name: Bottom Designator
Company: RENESAS



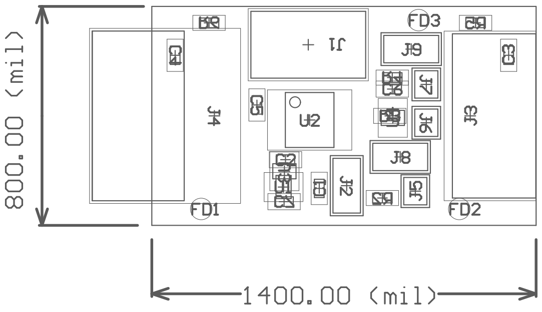
Filename: US082-ZSSC3123EVZ Rev A.PcbDoc
Date: 11/6/2024
Layer Name: Top 3D Body
Company: RENESAS



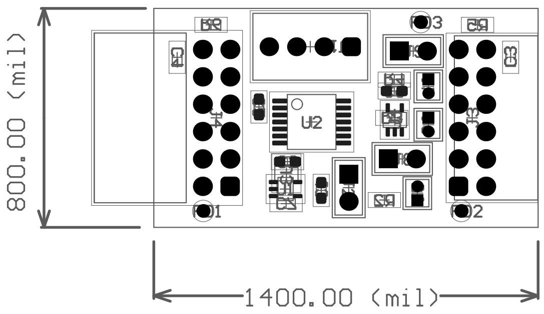
Filename: US082-ZSSC3123EVZ Rev A.PcbDoc
Date: 11/6/2024
Layer Name: Bottom 3D Body
Company: RENESAS



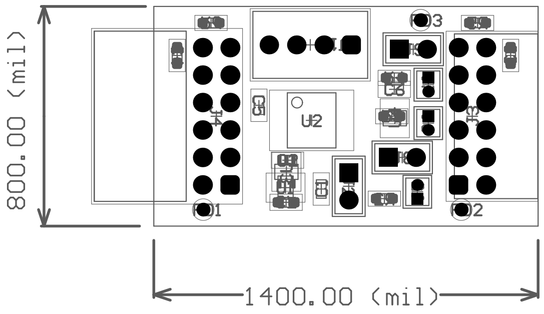
Filename: US082-ZSSC3123EVZ Rev A.PcbDoc
Date: 11/6/2024
Layer Name: Top Courtyard
Company: RENESAS



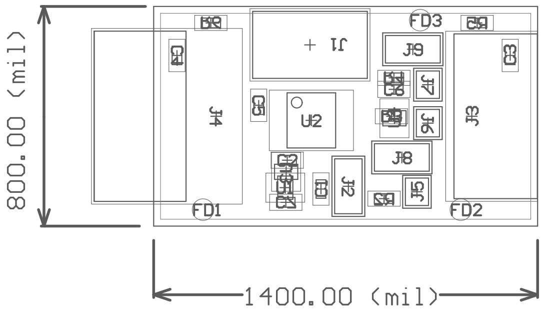
Filename: US082-ZSSC3123EVZ Rev A.PcbDoc
Date: 11/6/2024
Layer Name: Bottom Courtyard
Company: RENESAS



Filename: US082-ZSSC3123EVZ Rev A.PcbDoc
Date: 11/6/2024
Layer Name: Top Pad Master
Company: RENESAS

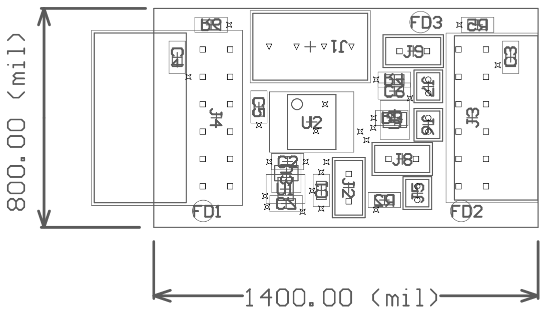


Filename:	US082-ZSSC3123EVZ Rev A.PcbDoc
Date:	11/6/2024
Layer Name:	Bottom Pad Master
Company:	RENESAS



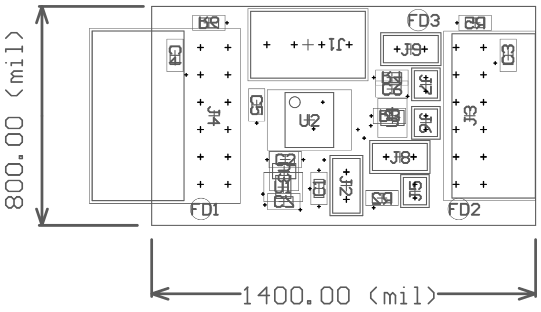
Filename: US082-ZSSC3123EVZ Rev A.PcbDoc
Date: 11/6/2024
Layer Name: Keep Out Layer
Company: RENESAS

Symbol	Count	Hole Size	Plated	Hole Type	Drill Layer Pair	Via/Pad	Pad Shape	Template
▽	4	43.31mil (1.100mm)	PTH	Round	Top Layer - Bottom Layer	Pad	(Mixed)	(Mixed)
○	6	27.56mil (0.700mm)	PTH	Round	Top Layer - Bottom Layer	Pad	(Mixed)	(Mixed)
¤	23	10.00mil (0.254mm)	PTH	Round	Top Layer - Bottom Layer	Via	Rounded	v61h25m0mx0
□	30	41.34mil (1.050mm)	PTH	Round	Top Layer - Bottom Layer	Pad	(Mixed)	(Mixed)
	63 Total							



Filename: US082-ZSSC3123EVZ Rev A.PcbDoc
Date: 11/6/2024
Layer Name: Drill Drawing For (Top Layer - Bottom Layer)
Company: RENESAS

Layer	Name	Material	Thickness	Constant	Board Layer Stack
	Top Overlay				▨
	Top Solder	SM-003	1.00mil	4	▨
	Top Surface Finish	Nickel, Gold	0.16mil		▨
1	Top Layer	CF-004	1.38mil		▨
	Dielectric 1	PP-008	3.10mil	4.1	▨
	Dielectric 2	PP-013	3.80mil	4.3	▨
2	Int1 (GND)	CF-004	1.38mil		▨
	Dielectric 3	Core-042	39.00mil	4.6	▨
3	Int2 (PWR)	CF-004	1.38mil		▨
	Dielectric 4	PP-013	3.80mil	4.3	▨
	Dielectric 5	PP-008	3.10mil	4.1	▨
4	Bottom Layer	CF-004	1.38mil		▨
	Bottom Surface Finish	Nickel, Gold	0.16mil		▨
	Bottom Solder	SM-003	1.00mil	4	▨
	Bottom Overlay				▨



Filename: US082-ZSSC3123EVZ Rev A.PcbDoc
Date: 11/6/2024
Layer Name: Drill Guide For (Top Layer - Bottom Layer)
Company: RENESAS